

Switch-mode Power Rectifier

D²PAK Power Surface Mount Package

MURB1660CT, NRVUB1660CTT4G

These state-of-the-art devices are designed for use in switching power supplies, inverters, and as free wheeling diodes.

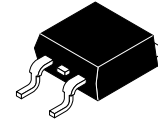
Features

- Package Designed for Power Surface Mount Applications
- Ultrafast 60 Nanosecond Recovery Times
- 175°C Operating Junction Temperature
- Epoxy Meets UL 94 V-0 @ 0.125 in
- High Temperature Glass Passivated Junction
- High Voltage Capability to 600 V
- Low Leakage Specified @ 150°C Case Temperature
- Short Heat Sink Tab Manufactured – Not Sheared!
- Similar in Size to Industrial Standard TO-220 Package
- NRV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free and are RoHS Compliant

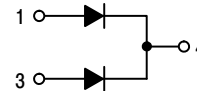
Mechanical Characteristics:

- Case: Epoxy, Molded, Epoxy Meets UL 94 V-0
- Weight: 1.7 Grams (Approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Device Meets MSL1 Requirements
- ESD Ratings:
 - ◆ Machine Model, C > 400 V
 - ◆ Human Body Model, 3B > 8000 V

ULTRAFAST RECTIFIER 16 AMPERES, 600 VOLTS



D²PAK
CASE 418B
STYLE 3



MARKING DIAGRAM



- A = Assembly Location
- Y = Year
- WW = Work Week
- U1660 = Specific Device Code
- G = Pb-Free Package
- AKA = Diode Polarity

ORDERING INFORMATION

| Device | Package | Shipping† |
|----------------|------------------------------|-------------------|
| MURB1660CTG | D ² PAK (Pb-Free) | 50 Units/Rail |
| MURB1660CTT4G | D ² PAK (Pb-Free) | 800 / Tape & Reel |
| NRVUB1660CTT4G | D ² PAK (Pb-Free) | 800 / Tape & Reel |

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, [BRD8011/D](#).

*For additional information on our Pb-Free strategy and soldering details, please download the [onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D](#).

MURB1660CT, NRVUB1660CTT4G

MAXIMUM RATINGS (Per Leg)

| Rating | Symbol | Value | Unit |
|---|---------------------------------|-------------|------------------|
| Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage | V_{RRM} V_{RWM} V_R | 600 | V |
| Average Rectified Forward Current (Rated V_R , $T_C = 150^\circ\text{C}$) Total Device | $I_{F(AV)}$ | 8.0 16 | A |
| Peak Repetitive Forward Current (Rated V_R , Square Wave, 20 kHz, $T_C = 150^\circ\text{C}$) | I_{FM} | 16 | A |
| Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz) | I_{FSM} | 100 | A |
| Operating Junction and Storage Temperature Range | T_J, T_{stg} | -65 to +175 | $^\circ\text{C}$ |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS (Per Leg)

| Rating | Symbol | Value | Unit |
|--|-----------------|-------|---------------------------|
| Maximum Thermal Resistance, Junction-to-Case | $R_{\theta JC}$ | 2.0 | $^\circ\text{C}/\text{W}$ |
| Maximum Thermal Resistance, Junction-to-Ambient (Note 1) | $R_{\theta JA}$ | 50 | $^\circ\text{C}/\text{W}$ |
| Temperature for Soldering Purposes: 1/8" from Case for 5 Seconds | T_L | 260 | $^\circ\text{C}$ |

1. See Chapter 7 for mounting conditions.

ELECTRICAL CHARACTERISTICS (Per Leg)

| Characteristic | Symbol | Max | Unit |
|--|----------|--------------|---------------|
| Maximum Instantaneous Forward Voltage (Note 2) ($I_F = 8.0$ Amp, $T_C = 150^\circ\text{C}$) ($I_F = 8.0$ Amp, $T_C = 25^\circ\text{C}$) | V_F | 1.20 1.50 | V |
| Maximum Instantaneous Reverse Current (Note 2) (Rated dc Voltage, $T_C = 150^\circ\text{C}$) (Rated dc Voltage, $T_C = 25^\circ\text{C}$) | i_R | 500 10 | μA |
| Maximum Reverse Recovery Time ($I_F = 1.0$ Amp, $di/dt = 50$ Amp/ μs) ($I_F = 0.5$ Amp, $I_R = 1.0$ Amp, $I_{REC} = 0.25$ Amp) | t_{rr} | 60 50 | ns |

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

2. Pulse Test: Pulse Width = 300 μs , Duty Cycle $\leq 2.0\%$.

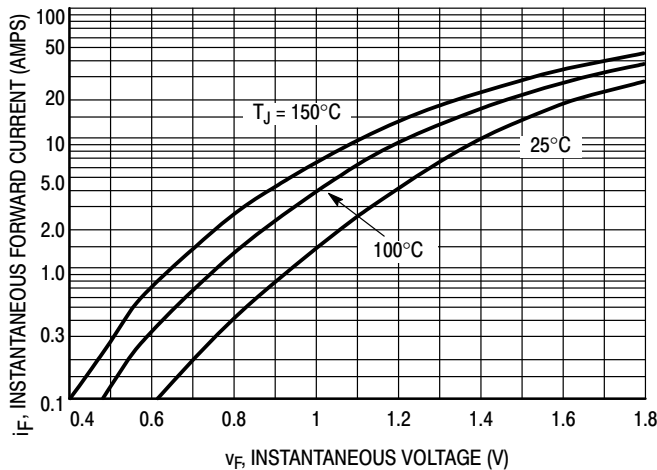


Figure 1. Typical Forward Voltage, Per Leg

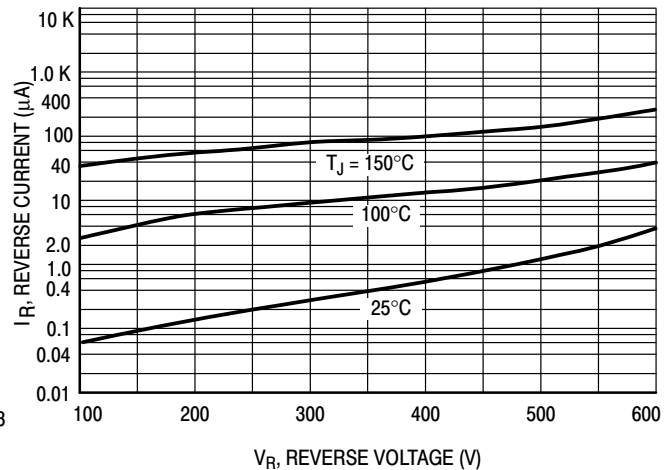


Figure 2. Typical Reverse Current, Per Leg

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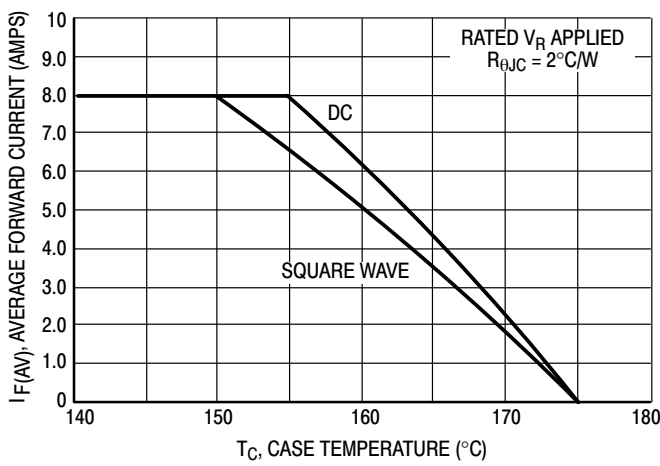


Figure 3. Current Derating, Case, Per Leg

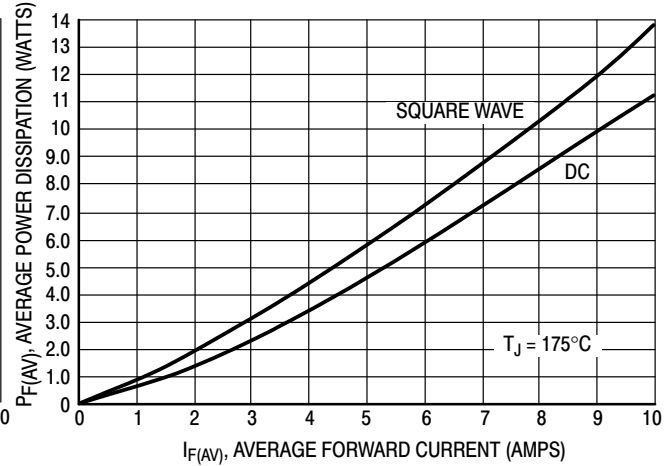


Figure 4. Power Dissipation, Per Leg

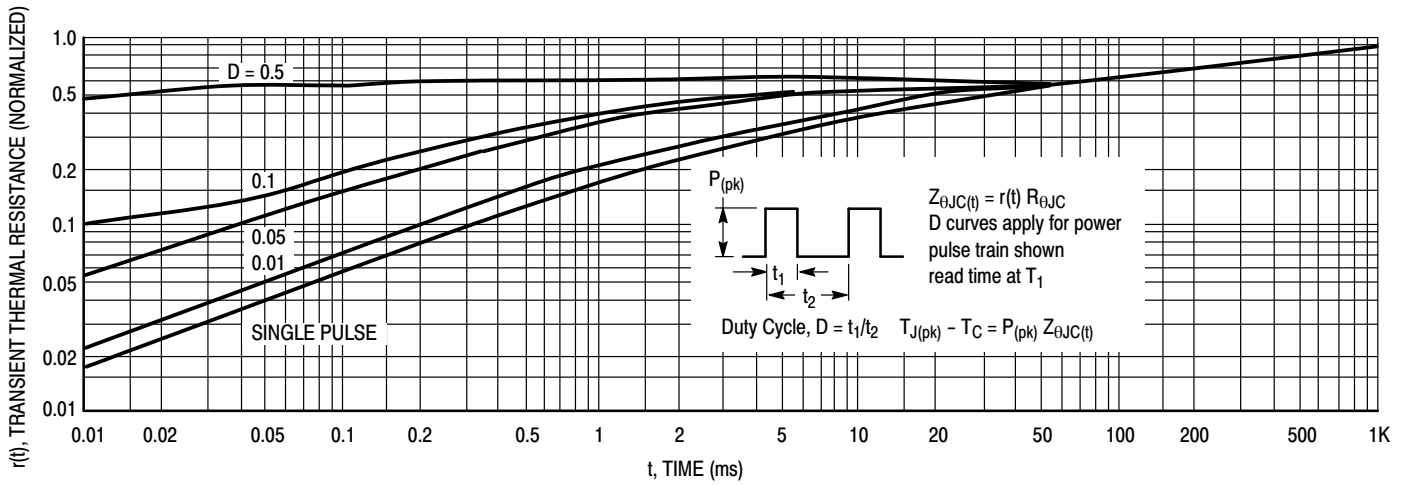


Figure 5. Thermal Response

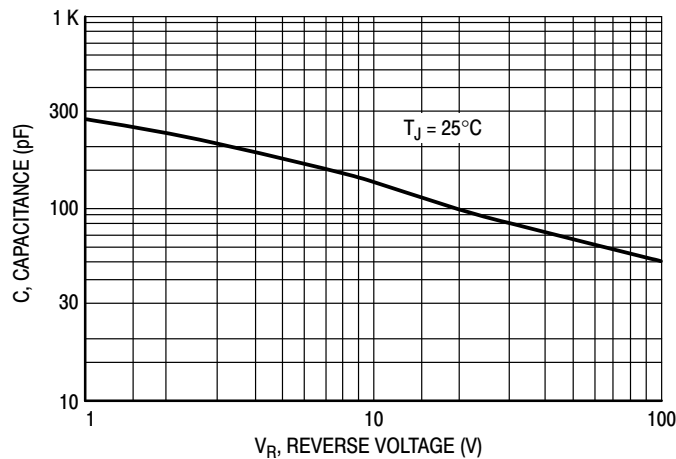


Figure 6. Typical Capacitance, Per Leg

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

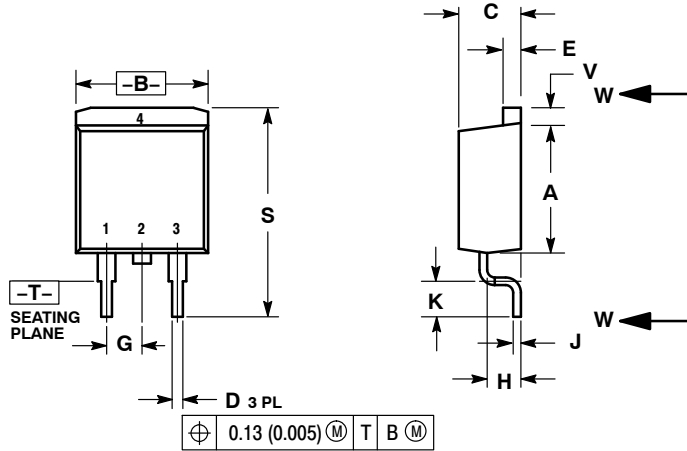
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D²PAK 3
CASE 418B-04
ISSUE L

DATE 17 FEB 2015

SCALE 1:1

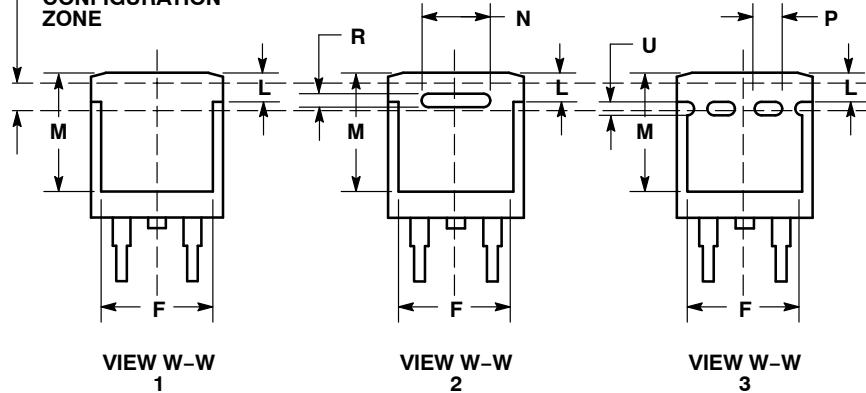


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. 418B-01 THRU 418B-03 OBSOLETE, NEW STANDARD 418B-04.

| DIM | INCHES | | MILLIMETERS | |
|-----|--------|-------|-------------|-------|
| | MIN | MAX | MIN | MAX |
| A | 0.340 | 0.380 | 8.64 | 9.65 |
| B | 0.380 | 0.405 | 9.65 | 10.29 |
| C | 0.160 | 0.190 | 4.06 | 4.83 |
| D | 0.020 | 0.035 | 0.51 | 0.89 |
| E | 0.045 | 0.055 | 1.14 | 1.40 |
| F | 0.310 | 0.350 | 7.87 | 8.89 |
| G | 0.100 | BSC | 2.54 | BSC |
| H | 0.080 | 0.110 | 2.03 | 2.79 |
| J | 0.018 | 0.025 | 0.46 | 0.64 |
| K | 0.090 | 0.110 | 2.29 | 2.79 |
| L | 0.052 | 0.072 | 1.32 | 1.83 |
| M | 0.280 | 0.320 | 7.11 | 8.13 |
| N | 0.197 | REF | 5.00 | REF |
| P | 0.079 | REF | 2.00 | REF |
| R | 0.039 | REF | 0.99 | REF |
| S | 0.575 | 0.625 | 14.60 | 15.88 |
| V | 0.045 | 0.055 | 1.14 | 1.40 |

VARIABLE CONFIGURATION ZONE



- | | | | | | |
|--|---|---|--|---|--|
| STYLE 1: PIN 1. BASE 2. COLLECTOR 3. EMITTER 4. COLLECTOR | STYLE 2: PIN 1. GATE 2. DRAIN 3. SOURCE 4. DRAIN | STYLE 3: PIN 1. ANODE 2. CATHODE 3. ANODE 4. CATHODE | STYLE 4: PIN 1. GATE 2. COLLECTOR 3. EMITTER 4. COLLECTOR | STYLE 5: PIN 1. CATHODE 2. ANODE 3. CATHODE 4. ANODE | STYLE 6: PIN 1. NO CONNECT 2. CATHODE 3. ANODE 4. CATHODE |
|--|---|---|--|---|--|

MARKING INFORMATION AND FOOTPRINT ON PAGE 2

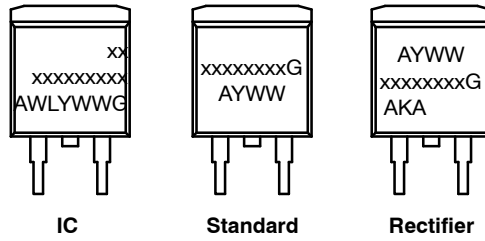
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CASE 418B-04
ISSUE L

DATE 17 FEB 2015

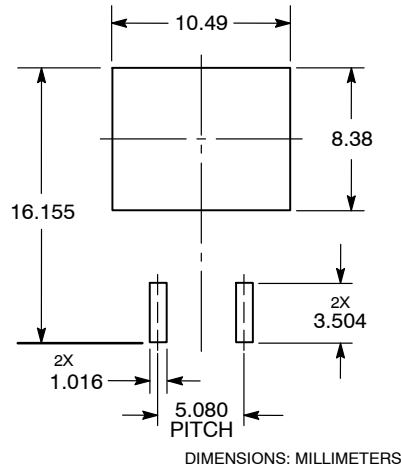
**GENERIC
MARKING DIAGRAM***



- xx = Specific Device Code
- A = Assembly Location
- WL = Wafer Lot
- Y = Year
- WW = Work Week
- G = Pb-Free Package
- AKA = Polarity Indicator

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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